

### Features

- **Fast Access Times at 0° to 70°C**
  - 2764 - 160 ns
  - 27128 - 200 ns
- **Programmed Using Intelligent Algorithm**
  - 21 V  $V_{PP}$
  - 2 Minutes for 27128
  - 1 Minute for 2764
- **JEDEC Approved Byte-wide Pin Configuration**
  - 2764 8K x 8 Organization
  - 27128 16K x 8 Organization
- **Low Power Dissipation**
  - 100 mA Active Current
  - 30 mA Standby Current
- **Military And Extended Temperature Range Available**
- **Silicon Signature®**

### Description

SEEQ's 2764 and 27128 are ultraviolet light erasable EPROMs which are organized 8K x 8 and 16K x 8 respectively. They are pin for pin compatible to JEDEC approved 64K and 128K EPROMs in all operational/programming modes. The devices have access times as fast as 160 ns over the 0° to 70°C temperature and  $V_{CC}$  tolerance range. The access time is achieved without

### Mode Selection

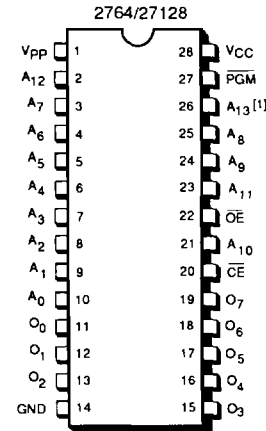
MODE	PINS	$\overline{CE}$ (20)	$\overline{OE}$ (22)	PGM (27)	$V_{PP}$ (1)	$V_{CC}$ (28)	Outputs (11-13, 15-19)
Read		$V_{IL}$	$V_{IL}$	$V_{IH}$	$V_{CC}$	$V_{CC}$	$D_{OUT}$
Output Disable		X	$V_{IH}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	High Z
Standby		$V_{IH}$	X	X	$V_{CC}$	$V_{CC}$	High Z
Program		$V_{IL}$	$V_{IH}$	$V_{IL}$	$V_{PP}$	$V_{CC}$	$D_{IN}$
Program Verify		$V_{IL}$	$V_{IL}$	$V_{IH}$	$V_{PP}$	$V_{CC}$	$D_{OUT}$
Program Inhibit		$V_{IH}$	X	X	$V_{PP}$	$V_{CC}$	High Z
Silicon Signature*		$V_{IL}$	$V_{IL}$	$V_{IH}$	$V_{CC}$	$V_{CC}$	Encoded Data

X can be either  $V_{IL}$  or  $V_{IH}$

\*For Silicon Signature:  $A_0$  is toggled,  $A_9 = 12V$ , and all other addresses are at a TTL low.

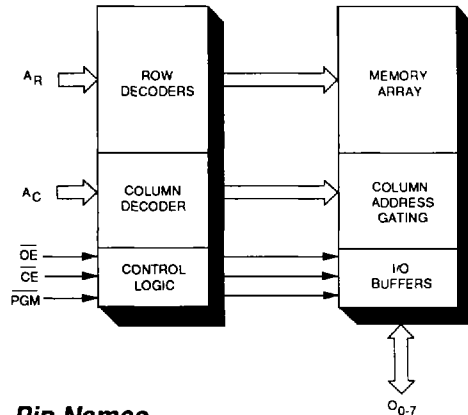
Silicon Signature is a registered trademark of SEEQ Technology, Inc.

### Pin Configuration



NOTE 1: PIN 26 IS A NO CONNECT ON THE 2764.

### Block Diagram



### Pin Names

$A_C$	ADDRESSES - COLUMN (LSB)
$A_R$	ADDRESSES - ROW
$\overline{CE}$	CHIP ENABLE
$\overline{OE}$	OUTPUT ENABLE
$O_0 - O_7$	OUTPUTS
PGM	PROGRAM

# 2764 27128

sacrificing power since the maximum active and standby currents are 100 mA and 30 mA respectively. The fast access times allow higher system efficiency by eliminating the need for wait states in today's 8 - or 16-bit micro-processors.

Initially, and after erasure, all bits are in the "1" state. Data is programmed by applying 21 V to  $V_{PP}$  and a TTL "0" to pin 27(program pin). The 2764 and 27128 may be programmed with an intelligent algorithm that is now available on commercial programmers. The program-

ming time is typically 5 ms/byte or 2 minutes for all 16K bytes of the 27128. The 2764 requires only half this time, about a minute for 8K bytes. This faster time improves manufacturing throughput time by hours over conventional 50 ms algorithms. Commercial programmers (e.g. Data I/O, Pro-log, Digelec, Kontron, and Stag) have implemented this fast algorithm for SEEQ's EPROMs. If desired, both EPROMs may be programmed using the conventional 50 ms programming specification of older generation EPROMs.

## Absolute Maximum Ratings

### Temperature

Storage ..... -65°C to +150°C

Under Bias ..... -10°C to +80°C

### All Inputs and Outputs

with Respect to Ground ..... +7 V to -0.6 V

### $V_{PP}$ During Programming

with Respect to Ground ..... +22 V to -0.6 V

### Voltage on $A_0$

with Respect to Ground ..... +15.5 V to -0.6 V

*\*COMMENT: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.*

## Recommended Operating Conditions

	2764 27128
$V_{CC}$ Supply Voltage <sup>[2]</sup>	5V ± 10%
Temperature Range (Read Mode)	(Ambient) 0°C to 70°C
$V_{PP}$ During Programming	21 ± 0.5 V

## DC Operating Characteristics During Read or Programming

Symbol	Parameter	Limits		Units	Test Conditions
		Min.	Max.		
$I_{IN}$	Input Leakage Current		10	μA	$V_{IN} = V_{CC}$ Max.
$I_{O}$	Output Leakage Current		10	μA	$V_{OUT} = V_{CC}$ Max.
$I_{PP}^{[1]}$	$V_{PP}$ Current	Read Mode	5	mA	$V_{PP} = V_{CC}$ Max.
		Prog. Mode	30	mA	$V_{PP} = 21.5$ V
$I_{CC1}^{[1]}$	$V_{CC}$ Standby Current		30	mA	$\overline{CE} = V_{IH}$
$I_{CC2}^{[1]}$	$V_{CC}$ Active Current		100	mA	$\overline{CE} = \overline{OE} = V_{IL}$
$V_{IL}$	Input Low Voltage	-0.1	0.8	V	
$V_{IH}$	Input High Voltage	2	$V_{CC} + 1$	V	
$V_{OL}$	Output Low Voltage		0.45	V	$I_{OL} = 2.1$ mA
$V_{OH}$	Output High Voltage	2.4		V	$I_{OH} = -400$ μA

### NOTES:

1.  $V_{CC}$  must be applied simultaneously or before  $V_{PP}$  and removed simultaneously or after  $V_{PP}$ .

**AC Operating Characteristics During Read**

Symbol	Parameter	Limits										Test Conditions
		2764-16		27XX-20		27XX-25		27XX-30		27XX-45		
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
$t_{AA}$	Address Access Time		160		200		250		300		450	$\overline{CE} = \overline{OE} = V_{IL}$
$t_{CE}$	Chip Enable to Data Valid		160		200		250		300		450	$\overline{OE} = V_{IL}$
$t_{OE}$	Output Enable to Data Valid		75		75		100		120		150	$\overline{CE} = V_{IL}$
$t_{DF}$	Output Enable to Output Float	0	60	0	60	0	60	0	105	0	130	$\overline{CE} = V_{IL}$
$t_{OH}$	Output Hold from Chip Enable, Addresses, or Output Enable whichever occurred first	0		0		0		0		0		$\overline{CE} = \overline{OE} = V_{IL}$

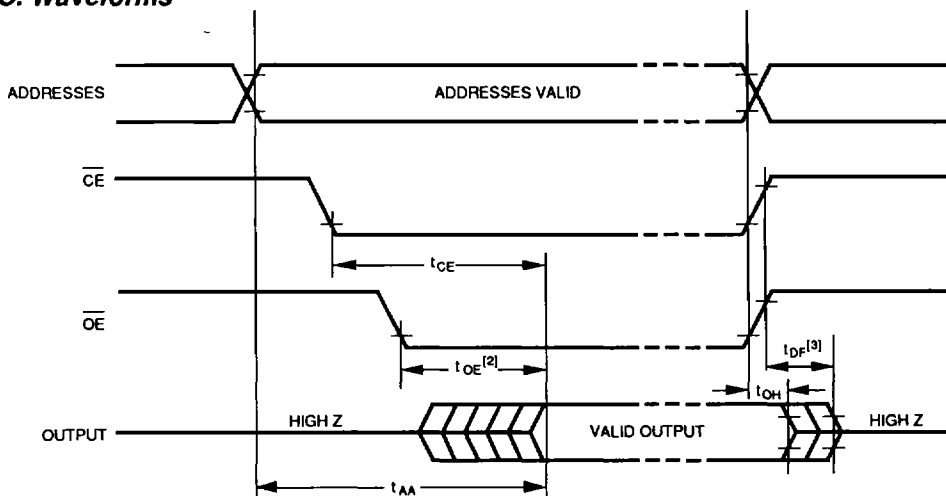
**Capacitance<sup>[1]</sup>**

Symbol	Parameter	Typ.	Max.	Unit	Conditions
$C_{IN}$	Input Capacitance	4	6	pF	$V_{IN} = 0 V$
$C_{OUT}$	Output Capacitance	8	12	pF	$V_{OUT} = 0 V$

**A.C. Test Conditions**

Output Load: 1 TTL gate and  $C_L = 100pF$   
 Input Rise and Fall Times:  $\leq 20 ns$   
 Input Pulse Levels: 0.45V to 2.4V  
 Timing Measurement Reference Level:  
 Inputs 1V and 2V  
 Outputs 0.8V and 2V

**A.C. Waveforms**



**NOTES:**

1. This parameter is sampled and is not 100% tested.
2.  $\overline{OE}$  may be delayed to  $t_{AA} - t_{OE}$  after the falling edge of  $\overline{CE}$  without impact on  $t_{AA}$ .
3.  $t_f$  is specified from  $\overline{OE}$  or  $\overline{CE}$ , whichever occurs first.
4. These are equivalent test conditions and actual test conditions are dependent on the tester.

Incorporated on SEEQ's EPROMs is Silicon Signature. Silicon Signature contains encoded data which identifies SEEQ as the EPROM manufacturer, the product's fab location, and programming information. This data is encoded in ROM to prevent erasure by ultraviolet light.

**Erasure Characteristics**

The 16K and 128K EPROMs are erased using ultraviolet light which has a wavelength of 2537 Angstroms. The integrated dose, i.e. intensity x exposure time, for erasure is a minimum of 15 watt-second/cm<sup>2</sup>. The EPROM should be placed within 1 inch of the lamp tube during erasure. Table 1 shows the typical EPROM erasure time for various light intensities.

**Table 1. Typical EPROM Erasure Time**

Light Intensity (Micro-Watts/cm <sup>2</sup> )	Erasure Time (Minutes)
15,000	20
10,000	30
5,000	55

**Silicon Signature**

Incorporated in SEEQ's EPROMs is a row of mask programmed read only memory (ROM) cells which is outside of the normal memory cell array. The ROM contains the EPROM's Silicon Signature. Silicon Signature contains data which identifies SEEQ as the manufacturer and gives the product code. This data allows programmers to match the programming specification against the product which is to be programmed. If there is verification, then the programmer can proceed programming.

Silicon Signature is activated by raising address A<sub>0</sub> to 12V ± 0.5V, bringing chip enable and output enable to a TTL low, having V<sub>CC</sub> at 5V, and having all addresses except A<sub>0</sub> at a TTL low. The Silicon Signature data is then accessed by toggling (using TTL) the column address A<sub>0</sub>. There are 2 bytes of data available (see Table 2). The data appears on outputs O<sub>0</sub> to O<sub>6</sub>, with O<sub>7</sub> used as an odd parity bit. This mode is functional at 25 ± 5°C ambient temperature.

**Table 2. Silicon Signature Bytes**

	A0	Hex Data
SEEQ Code (Byte 0)	V <sub>IL</sub>	94
Product Code (Byte 1)	V <sub>IH</sub>	40
2764	V <sub>IH</sub>	C1
27128	V <sub>IH</sub>	

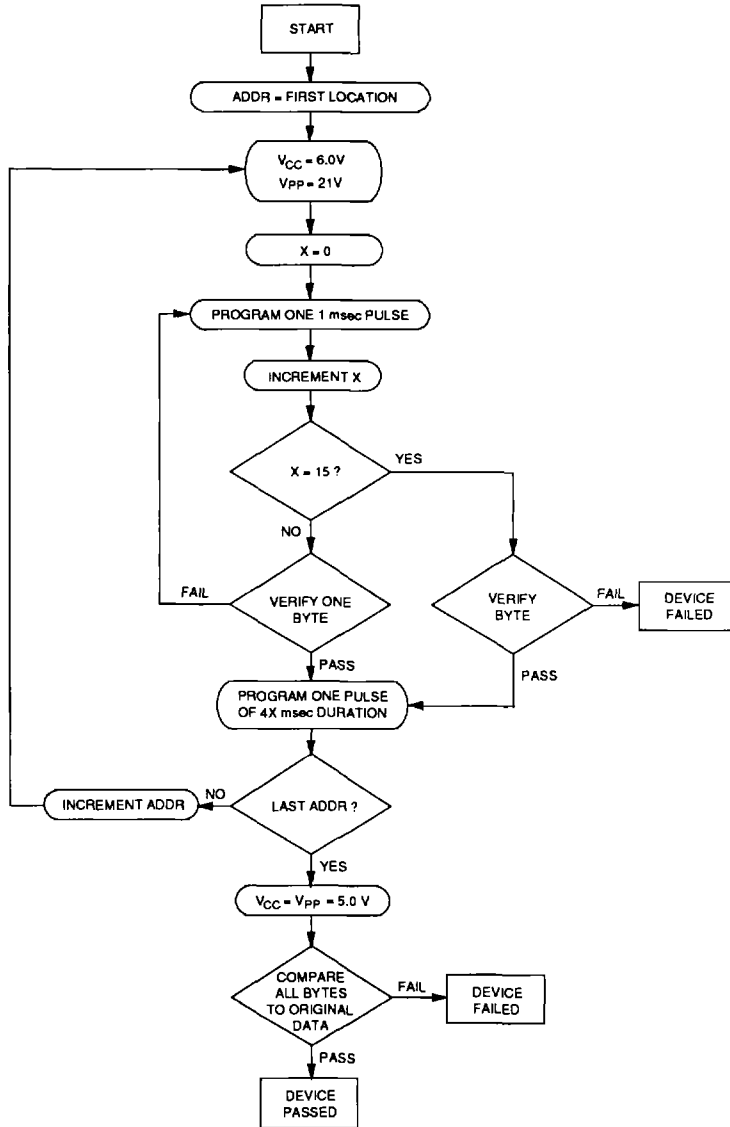
**Programming**

Both EPROMs may be programmed using an intelligent algorithm or with a conventional 50 msec programming pulse. The intelligent algorithm improves the total programming time by approximately 10 times over the conventional 50 msec algorithm. It typically requires only 1 and 2 minute programming time for all 64K and 128K bits respectively.

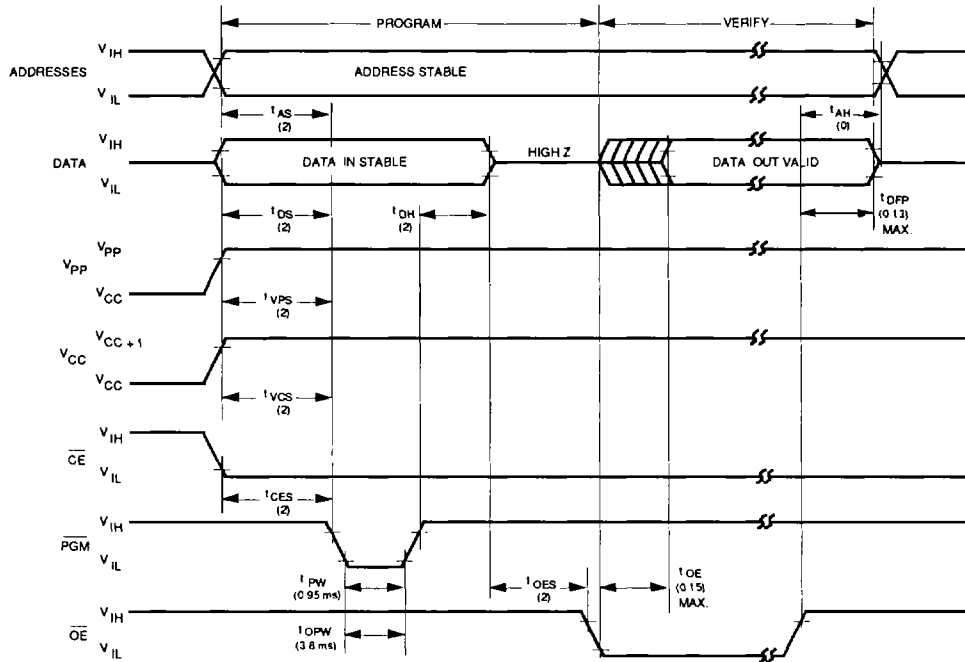
The intelligent algorithm requires V<sub>CC</sub> = 6V and V<sub>PP</sub> = 21V during byte programming. The initial program pulse width is one millisecond, followed by a sequence of one millisecond pulses. A byte is verified after each pulse. A single program pulse, with a time duration equal to 4 times the number of one millisecond pulses applied, is additionally given to the address after it is verified as being correctly programmed. A maximum of 15 one millisecond pulses per byte should be applied to each address. When the intelligent algorithm cycle has been completed, all bytes must be read at V<sub>CC</sub> = V<sub>PP</sub> = 5V.

Intelligent Algorithm Flowchart

EPROMS



**Intelligent Algorithm**



**NOTES:**

1. All times shown in ( ) are minimum and in  $\mu$ sec unless otherwise specified.
2. The input timing reference level is .8V for a  $V_{IL}$  and 2V for a  $V_{IH}$ .
3.  $t_{OE}$  and  $t_{OFP}$  are characteristics of the device but must be accommodated by the programmer.

**Intelligent Algorithm**

**AC Programming Characteristics<sup>(4)</sup>** TA = 25° ± 5°C, V<sub>CC</sub><sup>(1)</sup> = 6.0 V ± 0.25 V, V<sub>PP</sub> = V ± 0.5 V

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t <sub>AS</sub>	Address Setup Time	2			µs
t <sub>OES</sub>	OE Setup Time	2			µs
t <sub>DS</sub>	Data Setup Time	2			µs
t <sub>AH</sub>	Address Hold Time	0			µs
t <sub>DH</sub>	Data Hold Time	2			µs
t <sub>DFP</sub>	Output Enable to Output Float Delay	0		130	ns
t <sub>VPS</sub>	V <sub>PP</sub> Setup Time	2			µs
t <sub>VCS</sub>	V <sub>CC</sub> Setup Time	2			µs
t <sub>PW</sub> <sup>[2]</sup>	PGM Initial Program Pulse Width	0.95	1.0	1.05	ms
t <sub>OPW</sub> <sup>[3]</sup>	PGM Overprogram Pulse Width	3.8		63	ms
t <sub>CES</sub>	CE Setup Time	2			µs
t <sub>OE</sub>	Data Valid from OE			150	ns

**NOTES:**

- V<sub>CC</sub> must be applied simultaneously or before V<sub>PP</sub> and removed simultaneously or after V<sub>PP</sub>.
- Initial Program Pulse width tolerance is 1 msec ± 5 %.
- The length of the overprogram pulse will vary from 3.8 msec to 63 msec as a function of the iteration counter value X.
- For 50 ms programming, V<sub>CC</sub> = 5V ± 5%, T<sub>PW</sub> = 50 ms ± 10 %, and T<sub>OPW</sub> is not applicable.

**AC Test Conditions**

- Input Rise and Fall Times (10% to 90%) ..... 20 ns
- Input Pulse Levels ..... 0.45 V to 2.4 V
- Input Timing Reference Level ..... 0.8 V and 2.0 V
- Output Timing Reference Level ..... 0.8 V and 2.0 V

**Ordering Information**

